

1. A method of forming an integrated circuit package, the method comprising:  
forming a lead frame having a plurality of conductors and at least one alignment feature  
electrically isolated from the plurality of conductors;  
coupling at least some of the plurality of conductors to a semiconductor die; and  
encapsulating the semiconductor die and a portion of the lead frame with an insulating material.

2. The method of claim 1, further comprising removing the at least one alignment feature.

3. A method of forming an integrated circuit package, the method comprising:  
providing a plurality of conductors and at least one alignment feature;  
coupling at least some of the plurality of conductors to a semiconductor die; and  
encompassing the semiconductor die, the at least one alignment feature, and a portion of each of  
the plurality of conductors with an insulating material.

4. (Amended) A method of forming and testing an integrated circuit package, the  
method comprising:  
providing a plurality of conductors and at least one alignment feature;  
electrically coupling at least some of the plurality of conductors to a semiconductor die;  
encompassing the semiconductor die, the at least one alignment feature, and a portion of each of  
the plurality of conductors with an insulating material;  
coupling the at least one alignment feature encompassed by [an] the insulating material with a  
portion of [the] a testing device; and  
testing the integrated circuit package through at least some of the electrically coupled conductors.